# **Switching Transistor**

# **NPN Silicon**

#### **Features**

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	$V_{CEO}$	40	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	60	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	6.0	Vdc
Collector Current – Continuous	I <sub>C</sub>	600	mAdc
Collector Current – Peak	I <sub>CM</sub>	900	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) @T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate (Note 2) @T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

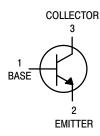
\*Transient pulses must not cause the junction temperature to be exceeded.

- 1. FR-5 =  $1.0 \times 0.75 \times 0.062$  in.
- 2. Alumina =  $0.4 \times 0.3 \times 0.024$  in. 99.5% alumina.



## ON Semiconductor®

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SOT-23 (TO-236) **CASÈ 318** STYLE 6

#### **MARKING DIAGRAM**



2X = Specific Device Code

M = Date Code\*

= Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

## ORDERING INFORMATION

Device	Device Package	
MMBT4401LT1G SMMBT4401LT1	1	3000 / Tape & Reel
MMBT4401LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Cha	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS			•	•	•
Collector – Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	40	-	Vdc	
Collector - Base Breakdown Voltage	$(I_C = 0.1 \text{ mAdc}, I_E = 0)$	V <sub>(BR)CBO</sub>	60	-	Vdc
Emitter-Base Breakdown Voltage	$(I_E = 0.1 \text{ mAdc}, I_C = 0)$	V <sub>(BR)EBO</sub>	6.0	-	Vdc
Base Cutoff Current	(V <sub>CE</sub> = 35 Vdc, V <sub>EB</sub> = 0.4 Vdc)	I <sub>BEV</sub>	-	0.1	μAdc
Collector Cutoff Current	(V <sub>CE</sub> = 35 Vdc, V <sub>EB</sub> = 0.4 Vdc)	I <sub>CEX</sub>	-	0.1	μAdc
ON CHARACTERISTICS (Note 3)					
DC Current Gain	$ \begin{aligned} &(I_C = 0.1 \text{ mAdc},  V_{CE} = 1.0 \text{ Vdc}) \\ &(I_C = 1.0 \text{ mAdc},  V_{CE} = 1.0 \text{ Vdc}) \\ &(I_C = 10 \text{ mAdc},  V_{CE} = 1.0 \text{ Vdc}) \\ &(I_C = 150 \text{ mAdc},  V_{CE} = 1.0 \text{ Vdc}) \\ &(I_C = 500 \text{ mAdc},  V_{CE} = 2.0 \text{ Vdc}) \end{aligned} $	h <sub>FE</sub>	20 40 80 100 40	- - - 300 -	-
Collector - Emitter Saturation Voltage	(I <sub>C</sub> = 150 mAdc, I <sub>B</sub> = 15 mAdc) (I <sub>C</sub> = 500 mAdc, I <sub>B</sub> = 50 mAdc)	V <sub>CE(sat)</sub>	- -	0.4 0.75	Vdc
Base – Emitter Saturation Voltage	V <sub>BE(sat)</sub>	0.75 -	0.95 1.2	Vdc	
SMALL-SIGNAL CHARACTERISTIC	s				
Current-Gain - Bandwidth Product	(I <sub>C</sub> = 20 mAdc, V <sub>CE</sub> = 10 Vdc, f = 100 MHz)	f <sub>T</sub>	250	_	MHz
Collector-Base Capacitance	$(V_{CB} = 5.0 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz})$	C <sub>cb</sub>	_	6.5	pF
Emitter-Base Capacitance	$(V_{EB} = 0.5 \text{ Vdc}, I_{C} = 0, f = 1.0 \text{ MHz})$	C <sub>eb</sub>	_	30	pF
Input Impedance	$(I_C = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$	h <sub>ie</sub>	1.0	15	kΩ
Voltage Feedback Ratio	$(I_C = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$	h <sub>re</sub>	0.1	8.0	X 10 <sup>-4</sup>
Small – Signal Current Gain	Small – Signal Current Gain (I <sub>C</sub> = 1.0 mAdc, V <sub>CE</sub> = 10 Vdc, f = 1.0 kHz)			500	-
Output Admittance	mittance ( $I_C = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz}$ )			30	μmhos
SWITCHING CHARACTERISTICS			-	-	-
Delay Time	(V <sub>CC</sub> = 30 Vdc, V <sub>EB</sub> = 2.0 Vdc,	t <sub>d</sub>	-	15	
Rise Time	I <sub>C</sub> = 150 mAdc, I <sub>B1</sub> = 15 mAdc)	t <sub>r</sub>	-	20	ns
Storage Time $(V_{CC} = 30 \text{ Vdc}, I_C = 150 \text{ n})$		t <sub>s</sub>	-	225	ne
Fall Time	1 1 45 A-d-)		_	30	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# **SWITCHING TIME EQUIVALENT TEST CIRCUITS**

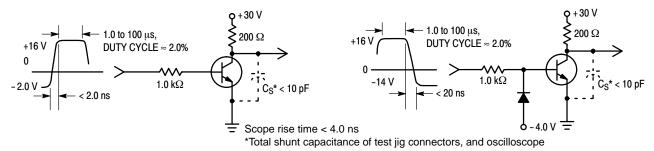


Figure 1. Turn-On Time

Figure 2. Turn-Off Time

<sup>3.</sup> Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

## TRANSIENT CHARACTERISTICS

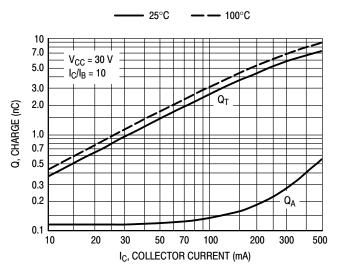


Figure 3. Charge Data

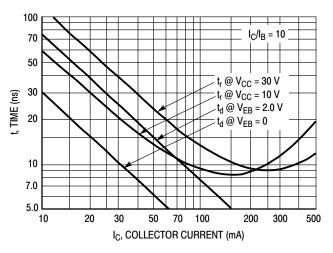


Figure 4. Turn-On Time

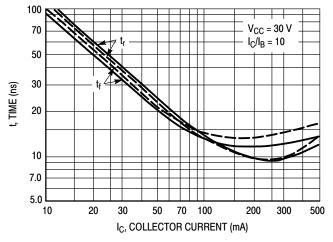


Figure 5. Rise and Fall Times

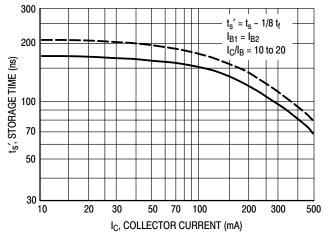


Figure 6. Storage Time

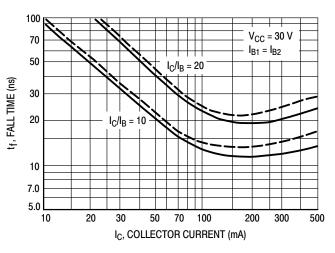


Figure 7. Fall Time

## SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE

 $V_{CE} = 10 \text{ Vdc}$ ,  $T_A = 25^{\circ}\text{C}$ ; Bandwidth = 1.0 Hz

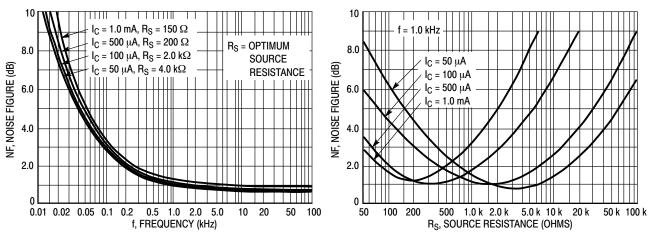


Figure 8. Frequency Effects

Figure 9. Source Resistance Effects

#### h PARAMETERS

$$V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz}, T_A = 25^{\circ}\text{C}$$

This group of graphs illustrates the relationship between  $h_{fe}$  and other "h" parameters for this series of transistors. To obtain these curves, a high–gain and a low–gain unit were selected from the MMBT4401LT1 lines, and the same units were used to develop the correspondingly numbered curves on each graph.

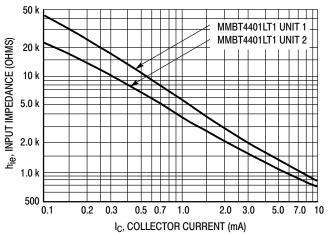


Figure 10. Input Impedance

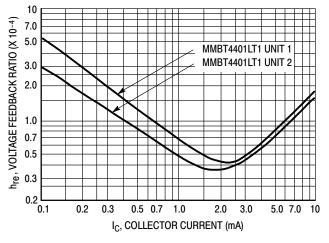


Figure 11. Voltage Feedback Ratio

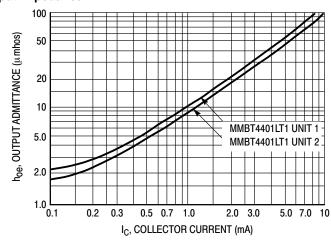


Figure 12. Output Admittance

## STATIC CHARACTERISTICS

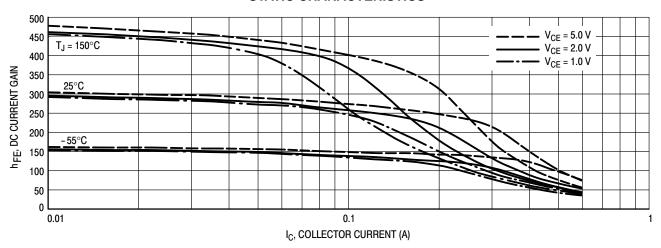


Figure 13. DC Current Gain

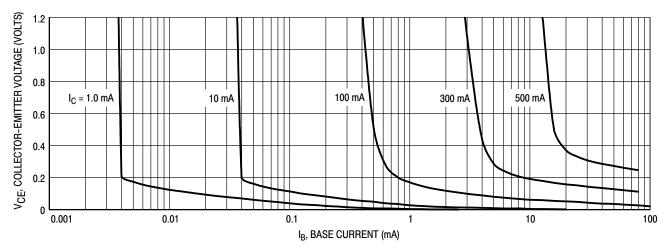


Figure 14. Collector Saturation Region

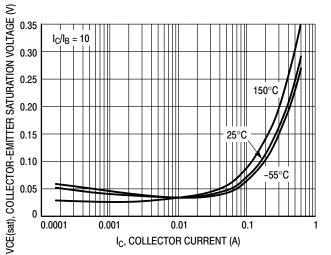


Figure 15. Collector–Emitter Saturation Voltage vs. Collector Current

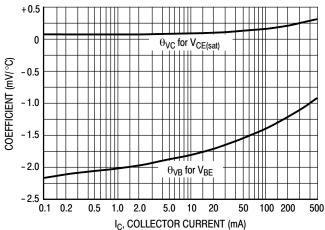


Figure 16. Temperature Coefficients

## STATIC CHARACTERISTICS

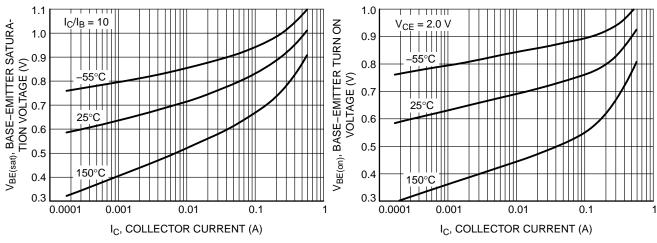


Figure 17. Base-Emitter Saturation Voltage vs. **Collector Current** 

Figure 18. Base-Emitter Turn On Voltage vs. **Collector Current** 

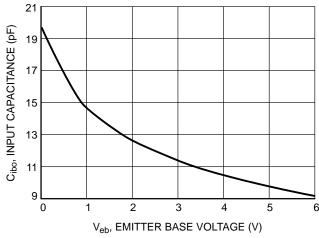


Figure 19. Input Capacitance vs. Emitter Base Voltage

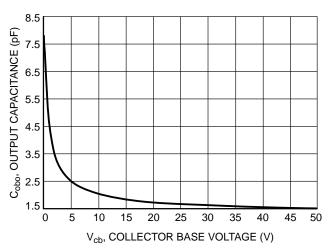


Figure 20. Output Capacitance vs. Collector **Base Voltage** 

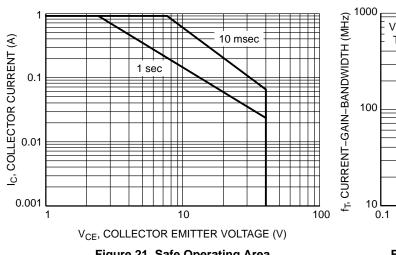


Figure 21. Safe Operating Area

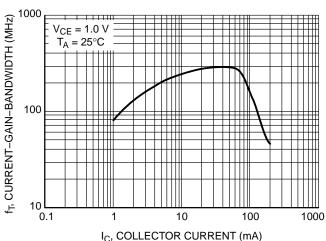
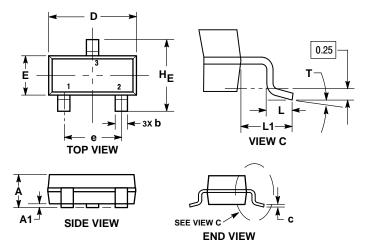


Figure 22. Current-Gain-Bandwidth Product

#### PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AR** 



#### NOTES:

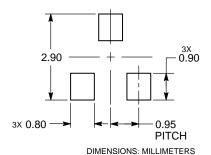
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
  MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
T	0°		10°	0°		10°

#### STYLE 6:

- PIN 1. BASE
  - EMITTER 2.
  - COLLECTOR

#### **RECOMMENDED** SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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